

ABSTRACT OF THE DISCLOSURE

A method for applying the solder mask onto solder pad spacings of a printed circuit board, mainly referring to the use of an ink-jet printer for printing the solder mask at the dense solder pad area on a printed circuit board, so as to prevent the solder mask from being coated onto solder pads in the dense solder pad area, thus improving the reliability of assembling processes for electronic products, and further providing merits of minimizing clearances between the solder mask and solder pads and increasing the adhesion of the solder mask.

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